

Electronic Patent Application Fee Transmittal

Application Number:	10519713			
Filing Date:	30-Dec-2004			
Title of Invention:	ADHESIVE FILM FOR SEMICONDUCTOR, METAL SHEET WITH SUCH ADHESIVE FILM, WIRING SUBSTRATE WITH ADHESIVE FILM, SEMICONDUCTOR DEVICE, AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE			
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Filer:	William Ivan Solomon/Qiana Graham			
Attorney Docket Number:	1204.44601X00			
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U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Miscellaneous:				
Printed copy of patent - no color	8001	4	3	12
Total in USD (\$)				1822